Product/Process Change Notice - PCN 25_0142 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. An acceptance or concern response should be submitted to ADI promptly. Any requests for samples of changed material or additional information must be made within 30 days of the notification. In accordance with JEDEC Standard 046, customers should acknowledge receipt of the PCN within 30 days of the PCN delivery. ADI contact information is listed below. Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change. After the acknowledgment, a lack of additional requests within 90 days constitutes acceptance of the change.

PCN Title:	Bond Wire Conversion from Gold to Copper for AD242x and AD243x A2B Products
Publication Date:	22-May-2025
Effectivity Date:	24-Aug-2025 *(the earliest date that a customer could expect to receive changed material)*
Revision Description:	Initial Release

Description Of Change:

Change of bond wire material from Gold (Au) to Copper (Cu) for select LFCSP/QFN products.
Mold compound changed from Sumitomo G770 to Sumitomo G700LA.

Additional changes to AD242X products:
- Die attach material changed from Ablestik 3230 to Hitachi EN4900GC.
- Bond wire thickness changed from 1.0 mil to 0.8 mil.

Reason For Change:

The conversion to Cu wire aligns with industry trend and ADI current and future corporate directives.

Impact of the change (positive or negative) on fit, form, function & reliability:

This change has no impact on fit, form, function or reliability.

Product Identification: *(this section will describe how to identify the changed material)*

Analog Device maintains full traceability by device marking/labeling/shipment documents. Change will be differentiated by date code.

Summary of Supporting Information:

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

Supporting Documents:

Attachment 1: Type: Qualification Results Summary

ADI_PCN_25_0142_Rev_-_AD242x_Qual report.pdf

Attachment 2: Type: Qualification Results Summary

ADI_PCN_25_0142_Rev_-_AD243x_Qual report.pdf

Attachment 3: Type: Delta Qualification Matrix

ADI_PCN_25_0142_Rev_-_Delta-Qualification-Matrix.xlsm

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models:

Added Parts On This Revision - Product Family / Model Number (42)

AD2426 / AD2426BCPZ	AD2426 / AD2426KCPZ	AD2426W / AD2426WCCSZ	AD2426W / AD2426WCCSZ-RL	AD2426W / AD2426WCCSZ01
AD2426W / AD2426WCCSZ01-RL	AD2426W / AD2426WCCSZ03	AD2426W / AD2426WCCSZ03-RL	AD2427 / AD2427BCPZ	AD2427 / AD2427KCPZ
AD2427W / AD2427WCCSZ	AD2427W / AD2427WCCSZ-RL	AD2427W / AD2427WCCSZ01	AD2427W / AD2427WCCSZ01-RL	AD2427W / AD2427WCCSZ03
AD2427W / AD2427WCCSZ03-RL	AD2428 / AD2428BCPZ	AD2428 / AD2428KCPZ	AD2428W / AD2428WCCSZ	AD2428W / AD2428WCCSZ-RL
AD2428W / AD2428WCCSZ01	AD2428W / AD2428WCCSZ01-RL	AD2428W / AD2428WCCSZ02	AD2428W / AD2428WCCSZ02-RL	AD2428W / AD2428WCCSZ03
AD2428W / AD2428WCCSZ03-RL	AD2428W / ADW95179Z-10	AD2428W / ADW95179Z-10RL	AD2428W / ADW95185Z-01	AD2428W / ADW95185Z-01RL
AD2428W / ADW95186Z-01	AD2428W / ADW95186Z-01RL	AD2428W / ADW95187Z-01	AD2428W / ADW95187Z-01RL	AD2428W / ADW95190Z
AD2428W / ADW95190Z-RL	AD2428W / ADW99038Z-RL	AD2433W / AD2433WCCPZ-RL	AD2433W / AD2433WCCPZ12	AD2433W / AD2433WCCPZ12-RL
AD2435W / AD2435WCCPZ13	AD2435W / AD2435WCCPZ13-RL			

Appendix B - Revision History:			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	22-May-2025	24-Aug-2025	Initial Release